



## Product Change Notice (PCN)

Date: **06/27/2024**

PCN Number: **PCN-0456757R**

To Our Customers:

We appreciate your use of our products. Our commitment in maintaining and improving processes is demonstrated by plans to enhance our product quality, reliability, and manufacturability. The purpose of this notice is to inform you of a product change.

Product(s) Affected: ***SJ1-253X-SMT-TR Series (SJ1-2533-SMT-TR, SJ1-2534-SMT-TR & SJ1-2535-SMT-TR)***

Reason(s) for Change: ***Manufacturing Improvement processes***

Description of Change: ***New Factory Location. Product re-engineered for improved manufacturability and production yield. See image below for reference and check CUI Devices website for updated drawing. Cosmetic differences may be visible and not affect the form fit and function of the product.***

PREVIOUS CUI DEVICES DETAIL / IMAGE

DESCRIPTION	MATERIAL	PLATING/COLOR
terminal 1	copper alloy	gold
terminal 2	copper alloy	gold
terminal 3	copper alloy	gold
terminal 4	copper alloy	gold
terminal 5	copper alloy	gold
housing	PABT UL94V-0	black

NEW CUI DEVICES DETAIL / IMAGE

DESCRIPTION	MATERIAL	PLATING/COLOR
terminal 1	copper alloy t=0.20	gold over nickel
terminal 2	copper alloy t=0.20	gold over nickel
terminal 3	copper alloy t=0.20	gold over nickel
terminal 4	copper alloy t=0.20	gold over nickel
terminal 5	copper alloy t=0.20	gold over nickel
housing	PA10T UL94V-0	black

**SOLDERABILITY**

parameter	conditions/description	min	typ	max	units
real storage	10-30°C, <70% humidity				°C
reflow soldering <sup>1</sup>	see reflow profile	255	260		°C
drying conditions <sup>2</sup>	parts in rack, 100°C for 4 hours parts removed from rack, 100°C for 4 hours				

note: 1. CUI Devices recommends to solder within 72 hours from opening vacuum packaging at a temperature 100°C & relative humidity 100%.  
2. After assembly, heat the by 100°C for 4 hours.

150°C  
30/sec. Max.  
200°C  
30-40 Sec.  
217°C  
( 60-180 sec. )  
6°C/sec. Max.  
Cooling in still air  
Above 217°C → 60-180 Sec.

- \* Time 25°C to Peak Temp. --- 8 Minutes Max.
- \* Time within 5°C of Actual Peak Temp. --- 20-40 Seconds

**SOLDERABILITY**

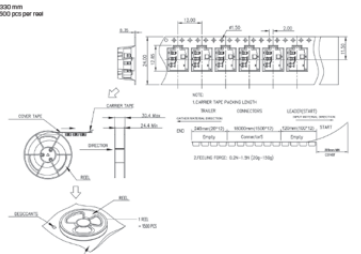
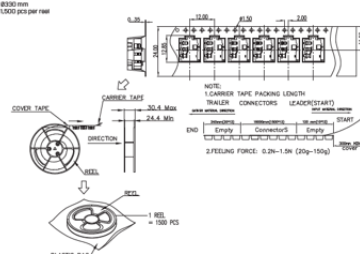
parameter	conditions/description	min	typ	max	units
real storage	5-25°C, 20-75% humidity				°C
reflow soldering	see reflow profile	255	260		°C

note: 1. CUI Devices recommends usage of the product within 24 hours after 168h in storage. After 24 hours, CUI Devices recommends drying the parts prior to use.

235°C  
Log. Temp (217°C)  
23°C/sec. Max.  
6°C/sec. Max.  
Peak Temp. 240-160°C  
240-160°C  
10-15 min.  
Reflow  
Cooling  
Room Temp (25°C)  
Preheating 10 sec. Min.

F-723-001

Revision: A

PREVIOUS CUI DEVICES DETAIL / IMAGE	NEW CUI DEVICES DETAIL / IMAGE
<p><b>PACKAGING</b></p> <p>UNITS: mm</p> <p>Reel Size: 8000 mm</p> <p>Reel QTY: 1,000 pcs per reel</p> 	<p><b>PACKAGING</b></p> <p>UNITS: mm</p> <p>Reel Size: 8000 mm</p> <p>Reel QTY: 1,000 pcs per reel</p> 

Affected Date Code: All orders placed after **05/15/2024**

Product Availability: *Pertaining to market availability*

PCN Approval:

Operations/Quality



Product Management

